

HRW0203A

Silicon Schottky Barrier Diode for Rectifying

REJ03G0154-0400Z

(Previous: ADE-208-014C)

Rev.4.00 Jan.06.2004

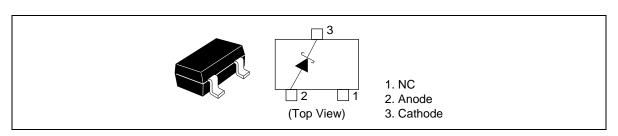
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HRW0203A	S5	MPAK

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM} *1	30	V	
Average rectified current	l _O * ¹	200	mA	
Non-Repetitive peak forward surge current	I _{FSM} *2	2	А	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. See from Fig.1 to Fig.5, with polyimide board.

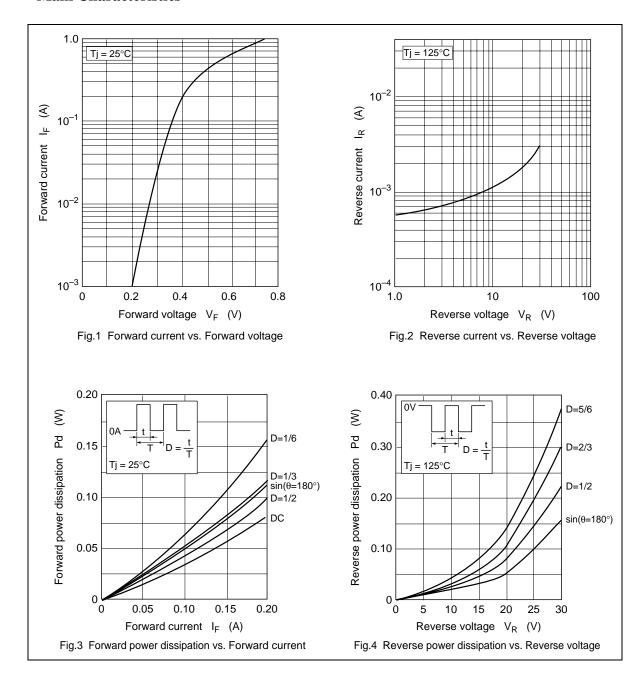
2. 50 Hz sine wave 1 pulse.

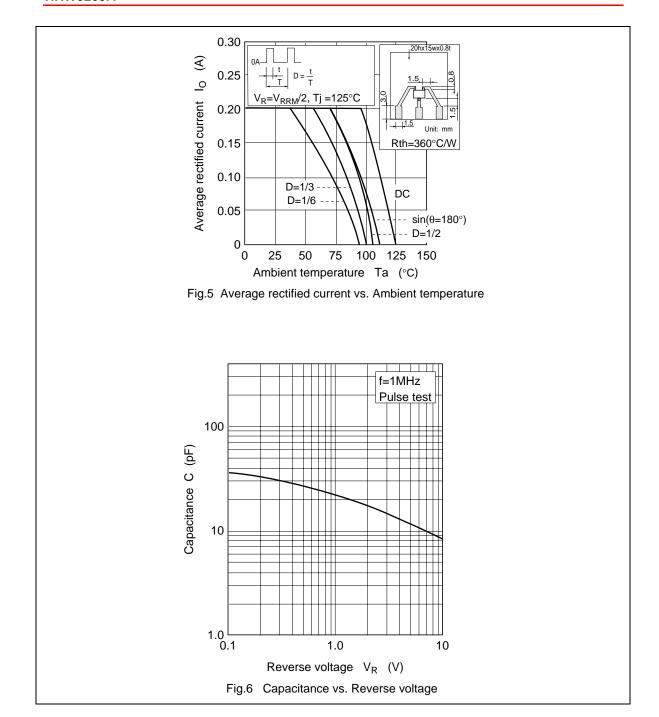
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

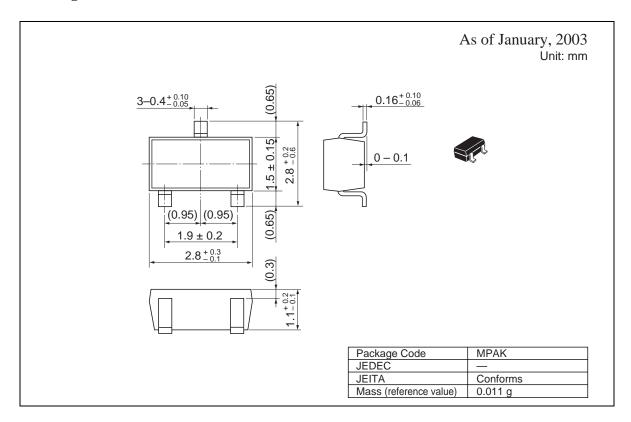
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.5	V	I _F = 200 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 30 V
Capacitance	С	_	40	_	pF	V _R = 0 V, f = 1 MHz

Main Characteristics





Package Dimensions



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